

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Hyeok-sang Oh	07/28/2008
RECEIVING PARTY DATA	
Name:	Samsung Electronics Co., LTD.
Street Address:	416, Maetan-dong, Yeongtong-gu,
Internal Address:	Suwon-si,
City:	Gyeonggi-do
State/Country:	KOREA, DEMOCRATIC PEOPLE'S REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12190131
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NAME OF SUBMITTER:	Yuanmin Cai
Total Attachments: 2 source=FIS920080110US1_SIGNEDSAMSUNGASSIGNMENT#page1.tif source=FIS920080110US1_SIGNEDSAMSUNGASSIGNMENT#page2.tif	

CH \$40.00 12190131

ASSIGNMENT

WHEREAS I, **Hyeok-sang Oh** of Donga 202-2402 Shindorim-Dong Kuro-Gu Seoul (hereinafter referred to as "ASSIGNOR"); have invented certain new and useful improvements in:

INTERCONNECT STRUCTURES COMPRISING CAPPING LAYERS WITH LOW DIELECTRIC CONSTANTS AND METHODS OF MAKING THE SAME

for which We are about to file an application for Letters Patent of the United States;

AND WHEREAS, **SAMSUNG ELECTRONICS CO., LTD.** (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of Korea, having a place of business at **416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Korea**, is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: 7/22/08

 L.S.
Hyeok-sang Oh